



Material Content Data Sheet



Sales Product Name		BSZ440N10NS3 G		Issued		1. August 2018		
MA#		MA001583326						
Package		PG-TSDSON-8-1		Weight*		36.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.830	2.30	2.30	22961	22961
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		98	
	non noble metal	zinc	7440-66-6	0.014	0.04		392	
	non noble metal	iron	7439-89-6	0.283	0.78		7840	
wire	non noble metal	copper	7440-50-8	11.505	31.83	32.66	318326	326656
	non noble metal	copper	7440-50-8	0.040	0.11	0.11	1101	1101
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1030
leadfinish	plastics	epoxy resin	-	1.918	5.31		53071	
	inorganic material	silicondioxide	60676-86-0	16.667	46.13	51.54	461149	515250
	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10239	10239
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2236	2236
solder	noble metal	silver	7440-22-4	0.028	0.08		780	
	non noble metal	tin	7440-31-5	0.023	0.06		624	
	non noble metal	lead	7439-92-1	1.078	2.98	3.12	29814	31218
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.078	0.22		2168	
	non noble metal	copper	7440-50-8	3.182	8.80	9.03	88036	90339
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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